

Dkt. No.: OP-093000139

**AMENDMENTS TO THE CLAIMS:**

1. (Currently amended) A water-cooling heat dissipation system used to dissipate heat generated by an electronic device, comprising:
  - a heat sink, mounted on the electronic device, the heat sink having a circulating loop connected to two ends of the heat sink;
  - ~~a water pump connected to the circulating loop at an inlet of the heat sink;~~
  - ~~a first cooling base installed in the circulating loop at an outlet of the heat sink; and~~
  - ~~a second cooling base installed in the circulating loop at an inlet of the heat sink between the heat sink and the water pump, the second cooling base having a cryogenic chip to cool down water flowing therethrough into icy state; and~~
  - ~~a water pump installed in the circulating loop between the first and the second cooling base.~~
2. (Original) The system as claimed in Claim 1, wherein the electronic device includes a central processing unit.
3. (Original) The system as claimed in Claim 1, wherein the first cooling base includes a heat sink mounted thereon and a cooling fan mounted on the heat sink.
4. (Currently amended) The system as claimed in Claim 1, wherein the heat sink includes an aluminum extrusion type of fins.
5. (Currently amended) The system as claimed in Claim 1, wherein the cryogenic chip includes a cold surface attached to the second cooling base and a hot surface.
6. (Original) The system as claimed in Claim 5, wherein the second cooling base further includes a heat sink mounted on the hot surface of the cryogenic chip and a cooling fan attached on the heat sink.
7. (Original) The system as claimed in Claim 6, wherein the heat sink includes an aluminum extrusion type of fins.

AMENDMENT

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